

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3020Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

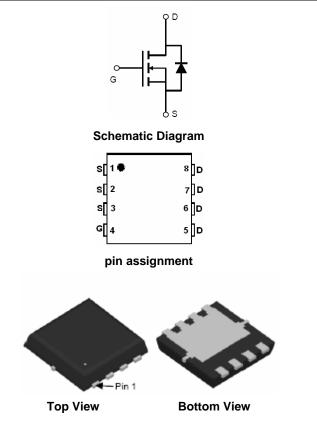
General Features

- V_{DS} =30V,I_D =20A
 R_{DS(ON)} <8mΩ @ V_{GS}=10V
 R_{DS(ON)} <12mΩ @ V_{GS}=4.5V
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

100% UIS TESTED! 100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3020Q	NCE3020Q	DFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Para	neter	Symbol	Limit	Unit
Drain-Source Voltage		Vds	30	V
Gate-Source Voltage		Vgs	±20	V
Drain Current-Continuous		Ι _D	20	А
Drain Current-Continuous(T _C =100)°C)	I _D (100℃)	14.1	A
Pulsed Drain Current		I _{DM}	80	A
Maximum Power Dissipation		P _D	20	W
Derating factor			0.27	W/℃
Single pulse avalanche energy ^{(№}	te 5)	E _{AS}	72	mJ
V _{DS} Spike (Note 6)	10µs	36	V	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	6.25	°C/W	1
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Electrical Characteristics (Tc=25 $^\circ\!\!\!\mathrm{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·		•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.5	2.2	V
Desia Course On Cheta Desistence	5	V _{GS} =10V, I _D =10A	-	6.8	8	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	8.8	12	mΩ
Forward Transconductance	g fs	V _{DS} =5V,I _D =10A	26	-	-	S
Dynamic Characteristics (Note4)	·		•			
Input Capacitance	Clss		-	1000	-	PF
Output Capacitance	C _{oss}	- V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	180.8	-	PF
Reverse Transfer Capacitance	C _{rss}		-	164.4	-	PF
Switching Characteristics (Note 4)	·		•			
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	V _{DD} =15V, R _L =0.75Ω	-	12	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =3Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg		-	17		nC
Gate-Source Charge	Q _{gs}	- V _{DS} =15V,I _D =10A,	-	2.8		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	3.9		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	I _S		-	-	20	А
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =10A	-	19	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	10	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negli	igible (turi	n-on is do	minated b	y LS+LD)

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, t \leq 10 sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production

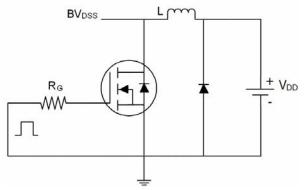
5. EAS condition:Tj=25 $^\circ C$,V_DD=15V,V_G=10V,L=0.5mH,Rg=25\Omega

6. The spike duty cycle 5% max, limited by junction temperature $T_{\rm J}(MAX){=}125^\circ~C$

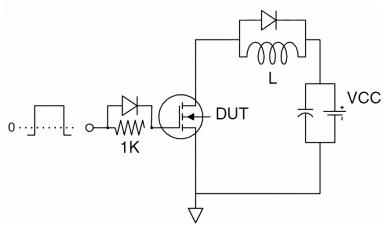


Test circuit

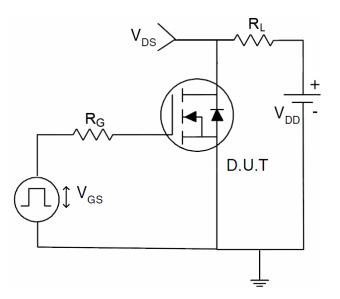
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:





V_{gs}=4.5V I_D=10A

150

175

125

75

100

15

25°Ċ

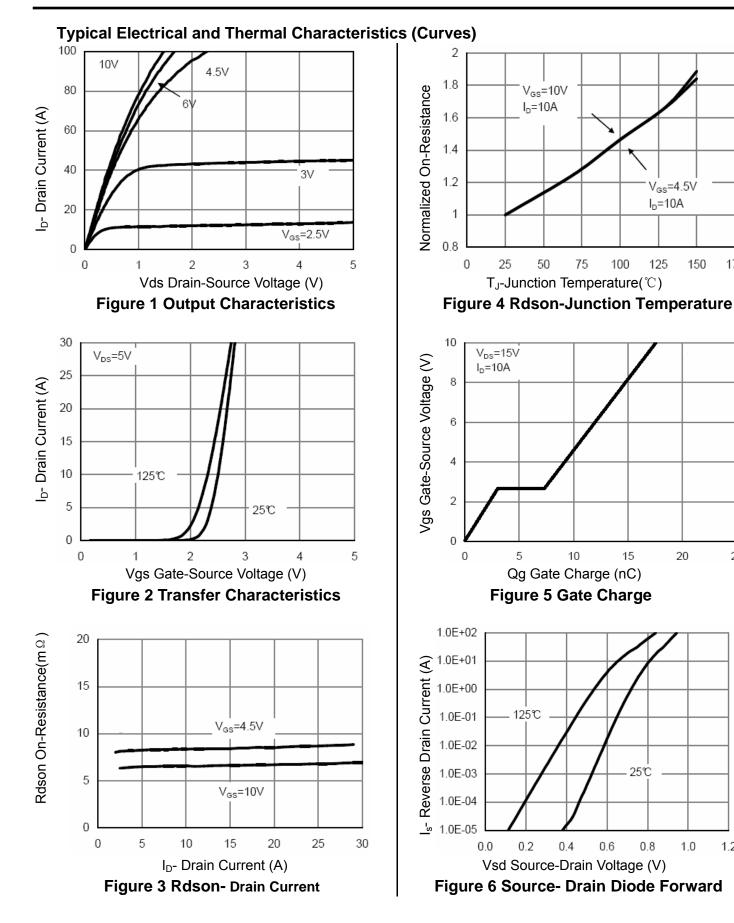
0.8

1.0

0.6

20

25

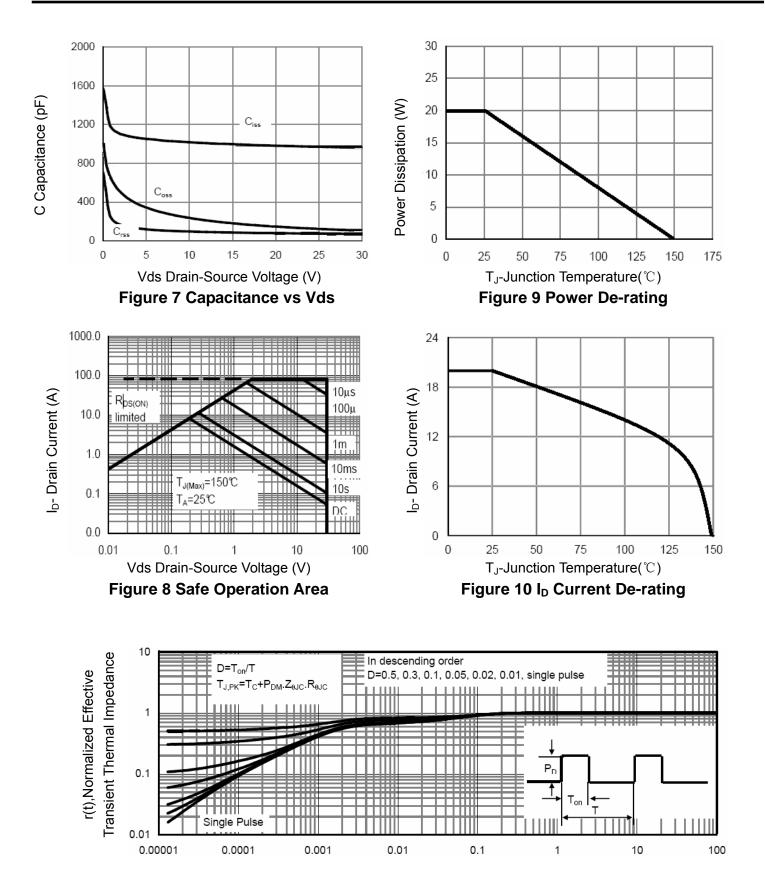


Wuxi NCE Power Co., Ltd

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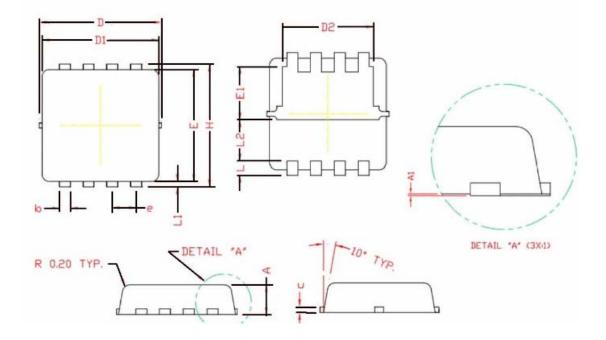
http://www.ncepower.com



Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance



DFN3.3X3.3-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
A	0.70	0.80	0.90	
A1	0.00	0.03	0.05	
b	0.24	0.30	0.35	
с	0.10	0.15	0.20	
D	3.25	3.32	3.40	
D1	3.05	3.15	3.25	
D2	2.40	2.50	2.60	
E	3.00	3.10	3.20	
E1	1.35	1.45	1.55	
е	0.65 BSC.			
H	3.20	3.30	3.40	
L	0.30	0.40	0.50	
L1	0.10	0.15	0.20	
L2	1	.13 REF		



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